



Product End-of-Life Disassembly Instructions

Product Category: External Options

Marketing Name / Model
[List multiple models if applicable.]

HP Spectre Folio 13 Convertible PC

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HPI products to remove components and materials requiring selective treatment, as defined by EU directive 2012/19/EC, Waste Electrical and Electronic Equipment (WEEE).

NOTE: Recyclers should sort plastic materials into resin streams for recycling based on the ISO 11469 plastic marking code on the plastic part. For any questions on plastic marking, please contact [HP's Sustainability Contact](#).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sq cm	1
Batteries, excluding Li-Ion batteries.	All types including standard alkaline, coin or button style batteries	
Li-Ion batteries. Include all Li-Ion batteries if more than one is provided with the product (such as a detachable notebook keyboard battery, RTC coin cell, etc.)	Battery(ies) are attached to the product by (<i>check all that apply with an "x" inside the "[]"</i>): [] screws [] snaps [x] adhesive [] other. Explain _____ NOTE: Add detailed removal procedures including required tools in the sections 3.1 and 3.2.	1
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps	1
Cathode Ray Tubes (CRT)		
Capacitors / condensers (Containing PCB/PCT)		
Electrolytic Capacitors/Condensers measuring greater		

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HPI instructions for this template are available at [EL-MF877-01](#)

Item Description	Notes	Quantity of items included in product
than 2.5 cm in diameter or height		
External electrical cables and cords	Power cords/Adapter	2
Gas Discharge Lamps		
Plastics containing Brominated Flame Retardants weighing > 25 grams (not including PCBs or PCAs already listed as a separate item above)		
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	
Components and waste containing asbestos		
Components, parts and materials containing refractory ceramic fibers		
Components, parts and materials containing radioactive substances		

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
<p>Specifications:</p> <ul style="list-style-type: none"> - working mat of the heating mat: L:30.5mmxW:20.2mm(W=10mm) - dimensions of the device: (L) 27.5mm x (W) 24.5(36)mm x (H)28.5mm - Semi-automatic separation mode: 55C / 5 min (with adjustable temperature and time) - Semi-automatic temperature support mode: 55C (with adjustable) - temperature range: 50~55° - Power: 100W(220V) - Weight: about 19.6kg 	
Description #2	Philip #1 / TORX T

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment including the required steps to remove the external enclosure:

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1. De-bonding Glass + LCM.
2. Cut off power by shipping mode switch, and release cables (WWAN/WLAN/e-DP/Antenna/Camera...).
3. Disassembly WWAN PCB/Module/ IR-camera bracket.
4. Disassembly fixture screw between LCD COVER & Inner TOP.
5. Disassembly fixture screw between Hinge Arm top & Inner BTM.
6. Disassembly LCD ASSY/KB-Deck and leather unit (/s battery & TP module).
7. Disassembly SPK Box(/s driver & WIFI module) from KB-Deck..
8. Disassembly LCD ASSY & KB-Deck(/s MB)
9. Disassembly HINGE base on KB-Deck.
10. Disassembly MB/SSD module on KB-Deck.

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

LCD side:

- a. To reduce bonding glass adhesive stickiness by heat gun (working Temp:-60° ,times-90s).
- b. Factory de-bonding is by heating jig.
- c. De-bonding tools: 0.55mm thickness Pick, Ø>30.0mm sucker to disassemble GS.
- d. De-bonding frequency: A → B → C.
- e. De-bonding action: Heating glass and separate it by sucker at same time, then to pick it up by pick.

Step 1 De-bonding Glass + LCM.

LCD side:

- a. Disassembly all of cable (IR camera cable L/R · TS PCB FFC · e-DP cable · WWAN/WLAN cable · SIM card FPC).
- b. Disassembly Antenna cable (main/aux).
- c. Before disassembly WWAN/WLAN cable, need to release elastic adhesive on PCB.
- d. Disassembly WWAN/WLAN PCB by screw driver (WWAN SKU screw*5pcs, WLAN SKU screw*4pcs).

Step 2 Cut off power and release cables.

LCD side:

- a. After disassembly screw*11, than release IR support bracket.

Step 3 Disassembly WWAN PCB/Module/ IR-camera bracket/.

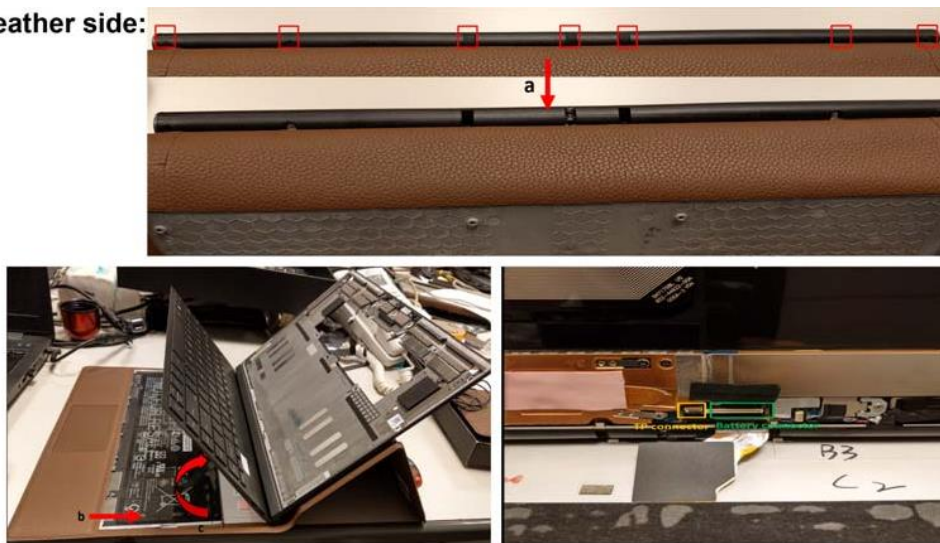
Step 4 Disassembly fixture screw between LCD COVER & Inner TOP.

LCD side:



- a. Release leather up side.
 - b. Lift up LCD COVER to reveal fixtured screw on HINGE ARM TOP*10pcs.
- Step 5 Disassembly fixture screw between Hinge Arm top & Inner BTM.

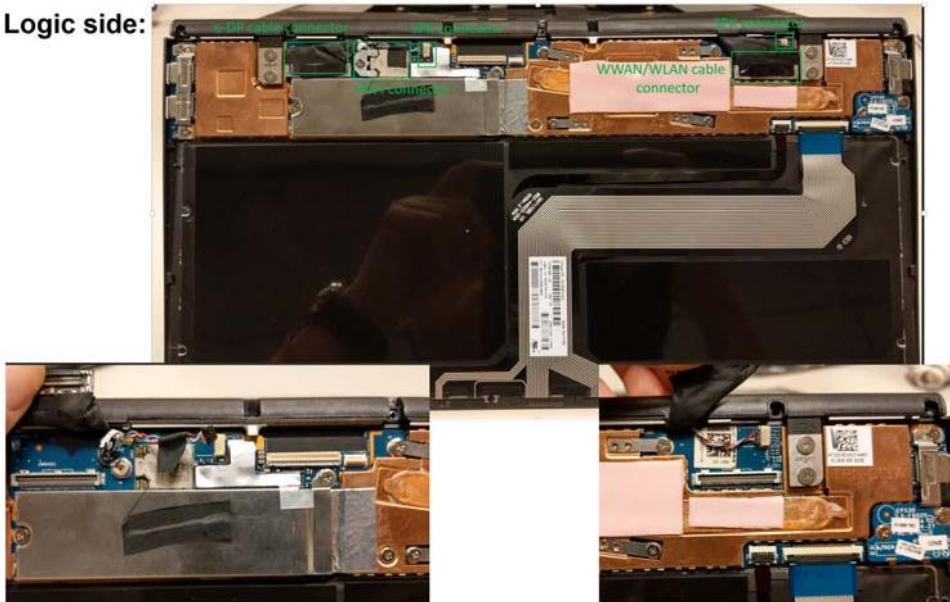
Leather side:



- a. Release logic screw rubber *7pcs.
- b. Slide out KB-Deck .
- c. Lift up KB-Deck to reveal MB.
- d. Then to release Battery connector / TP connector to cut off logic up and leather unit connection.

Step 6 Disassembly LCD ASSY/KB-Deck and leather unit (/s battery & TP module).

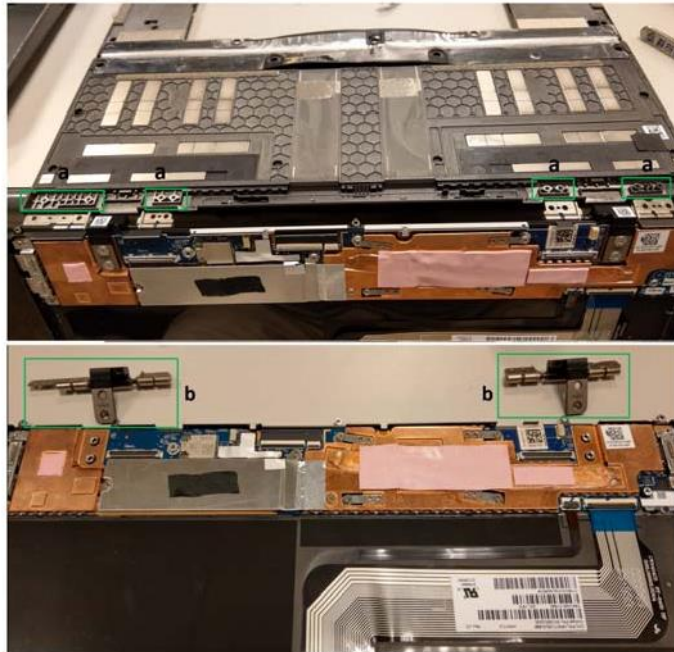
Logic side:



a. To release e-DP /WWAN/WLAN cable connector, WIFI cable connector, SPK connector .

Step 7 Disassembly SPK Box (/s driver & WIFI module) from KB-Deck.

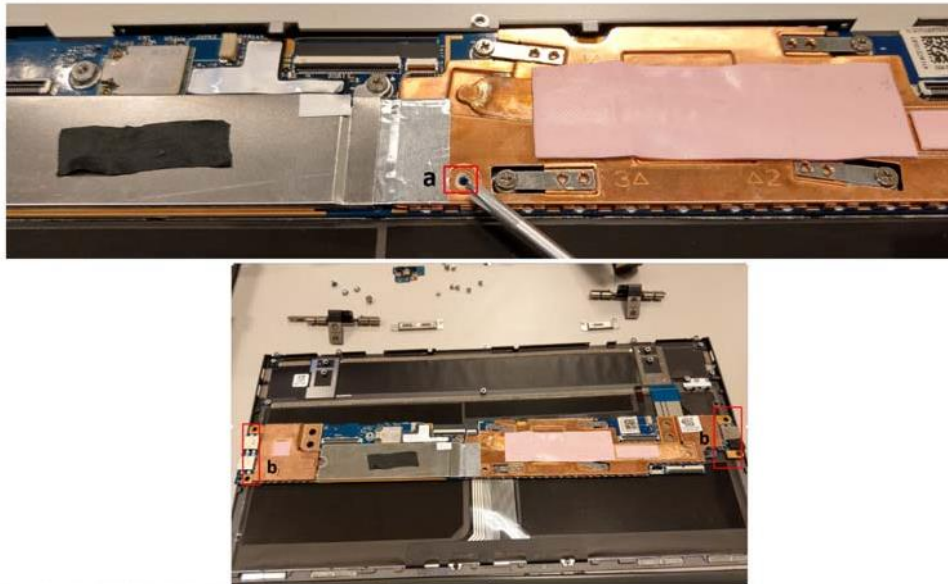
LCD-Logic side:



- a. To unscrew *4pcs between hinge and HINGE ARM TOP cover, then we can separate LCD COVER & KB-Deck.
- b. To unscrew *4pcs between hinge and KB-Deck.

Step 8 Disassembly LCD ASSY & KB-Deck (/s MB).
Step 9 Disassembly HINGE base on KB-Deck.

Logic side:



- a. To unscrew screw on thermal module and KB-Deck.
- b. To unscrew screw on thermal module and KB-Deck, then we can separate MB/KB-Deck/IO-support bracket.

Step 10 Disassembly MB/SSD module on KB-Deck.